

### Description

#### Features

- 20V, 85A
- $R_{DS(ON)}$  Typ = 1.75mΩ @  $V_{GS} = 4.5V$
- $R_{DS(ON)}$  Typ = 2.2mΩ @  $V_{GS} = 2.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100%  $\Delta V_d$ s TESTED!



Schematic Diagram

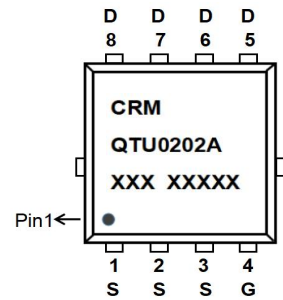
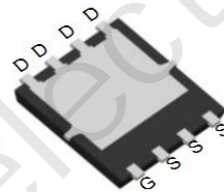
#### Application

- Load Switch
- PWM Application
- Power Management

Top View



Bottom View



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQTU0202A	CRMQTU0202A	PDFN3.3x3.3-8L	TAPING	13"	5000	60000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	20	V
$V_{GS}$	Gate-to-Source Voltage	±12	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ C$	85
		$T_C = 100^\circ C$	51
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	340	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	144	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ C$	25
$R_{\theta JC}$	Thermal Resistance, Junction to Case	5	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

### Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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#### Off Characteristics

V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±12V	-	-	±100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.4	0.6	1	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	1.75	2.3	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 10A	-	2.2	2.9	mΩ

#### Dynamic Characteristics

C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 10V, f = 1MHz	-	5358	-	pF
C <sub>oss</sub>	Output Capacitance		-	735	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	632	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 4.5V V <sub>DS</sub> = 10V, I <sub>D</sub> = 30A	-	64	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	12	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	19	-	nC

#### Switching Characteristics

t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 4.5V, V <sub>DD</sub> = 10V I <sub>D</sub> = 30A, R <sub>GEN</sub> = 3Ω	-	20	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	47	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	117	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	120	-	ns

#### Drain-Source Diode Characteristics and Max Ratings

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A	-	-	85	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	340	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage		-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time		-	22	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	12	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2. E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, R<sub>G</sub>=25ohm, L=0.5mH, I<sub>AS</sub>=24A
  3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

## Typical Performance Characteristics

Figure 1: Output Characteristics

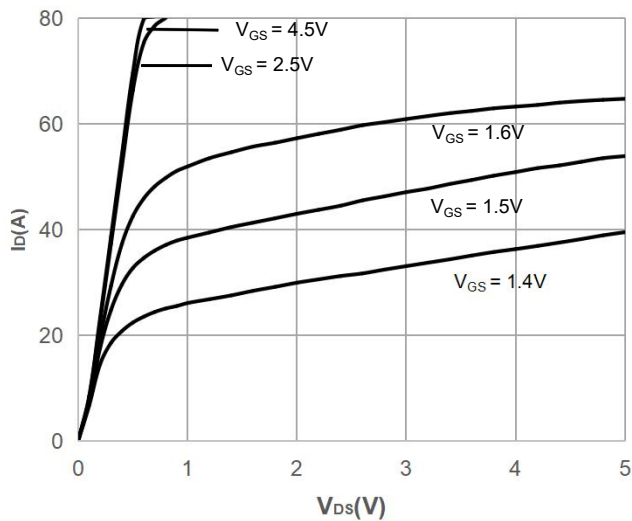


Figure 2: Typical Transfer Characteristics

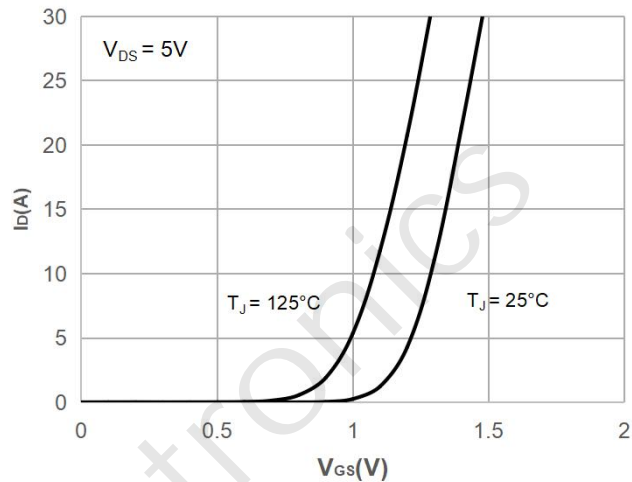


Figure 3: On-resistance vs. Drain Current

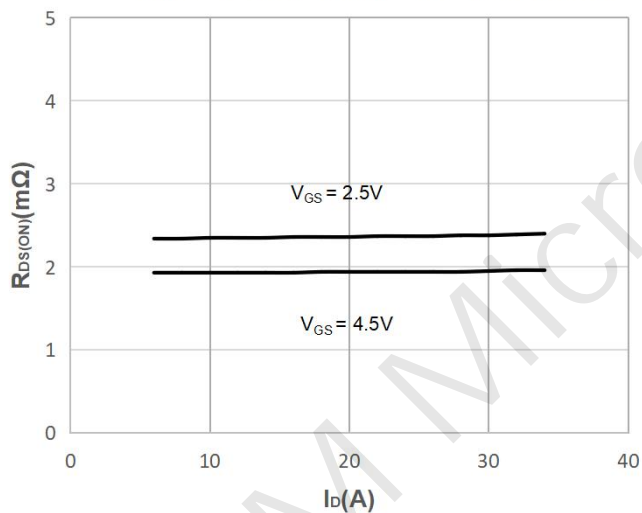


Figure 4: Body Diode Characteristics

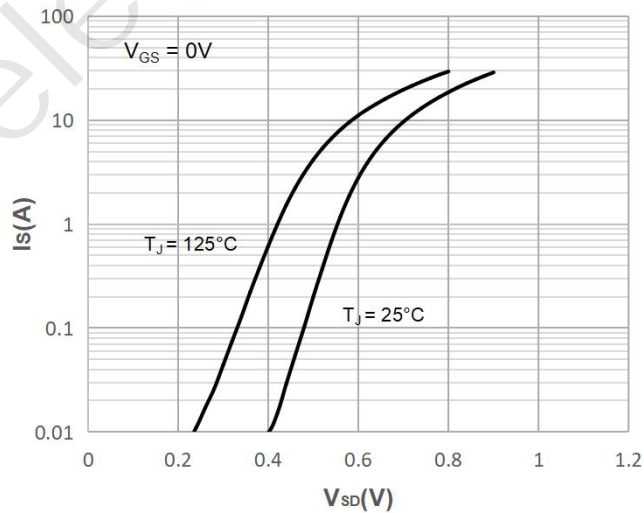


Figure 5: Gate Charge Characteristics

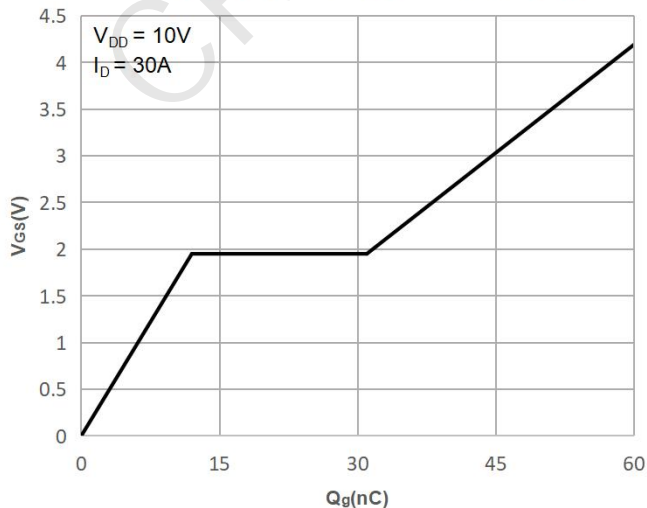
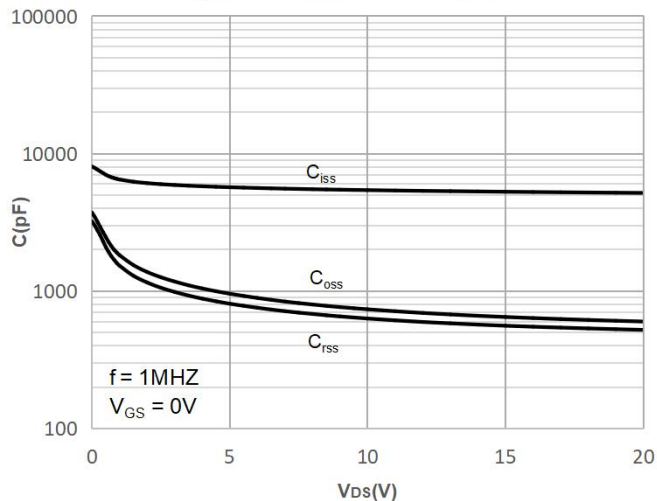


Figure 6: Capacitance Characteristics



## Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

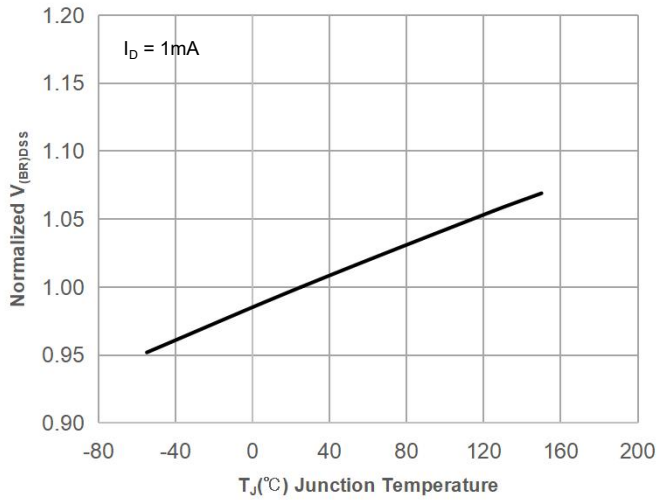


Figure 8: Normalized on Resistance vs. Junction Temperature

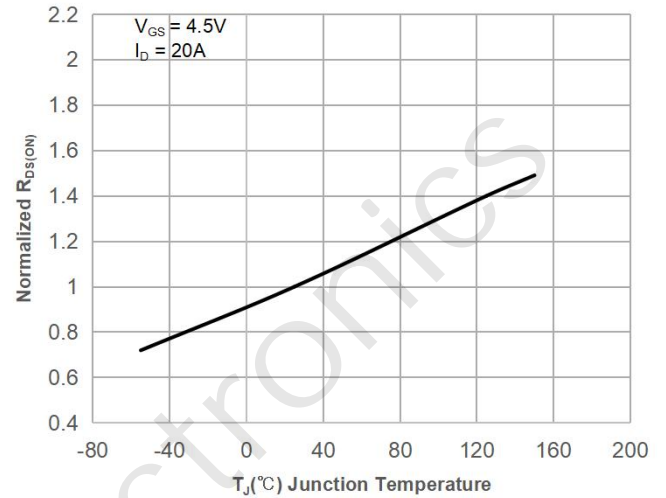


Figure 9: Maximum Safe Operating Area

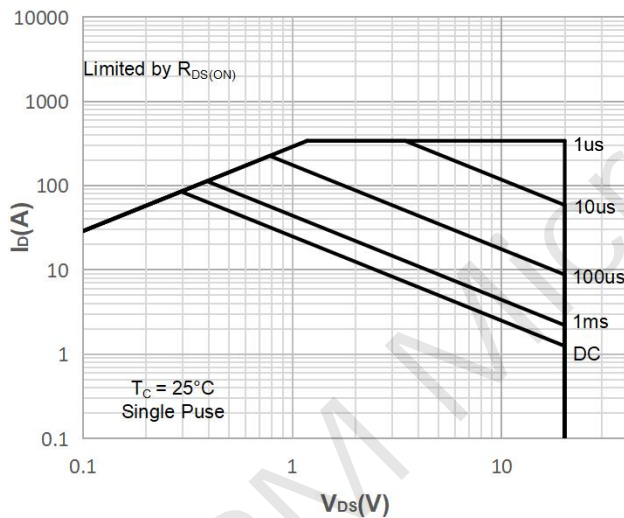


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

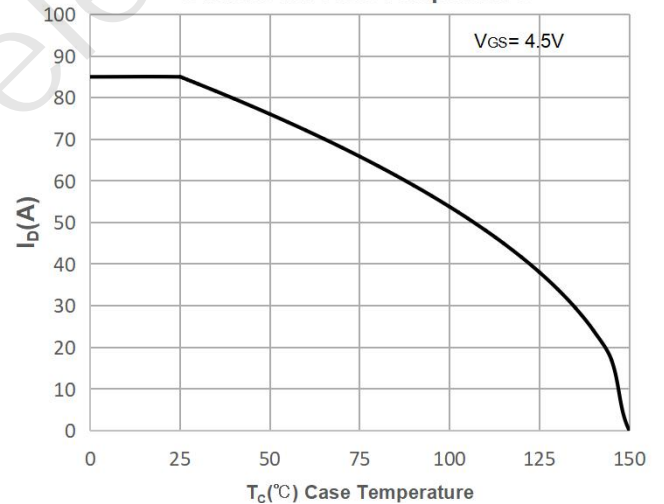


Figure 11: Normalized Maximum Transient Thermal Impedance

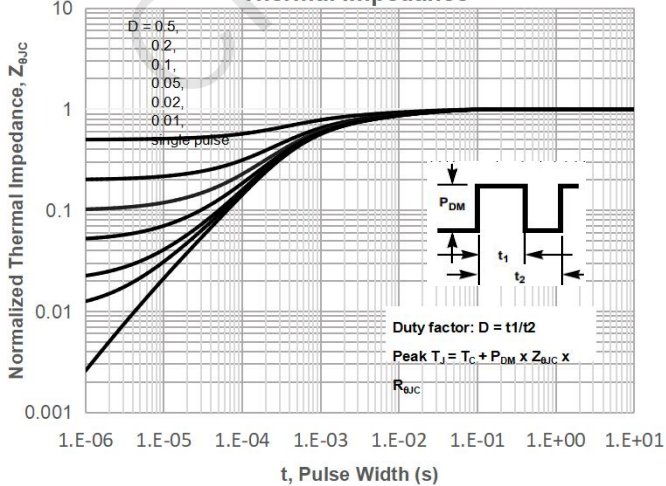
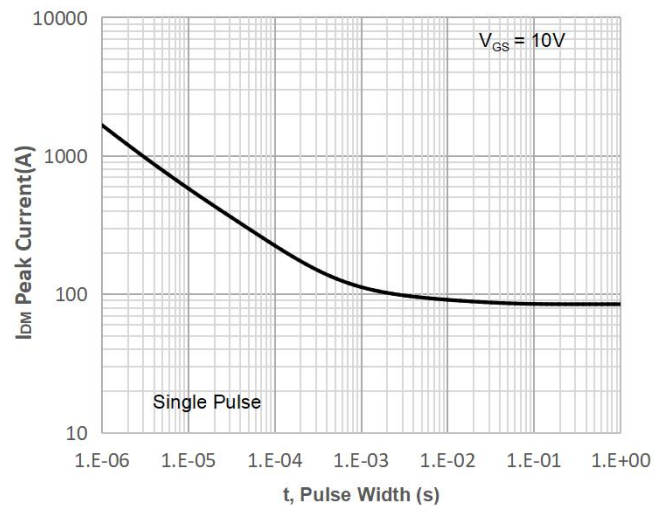


Figure 12: Peak Current Capacity



## Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

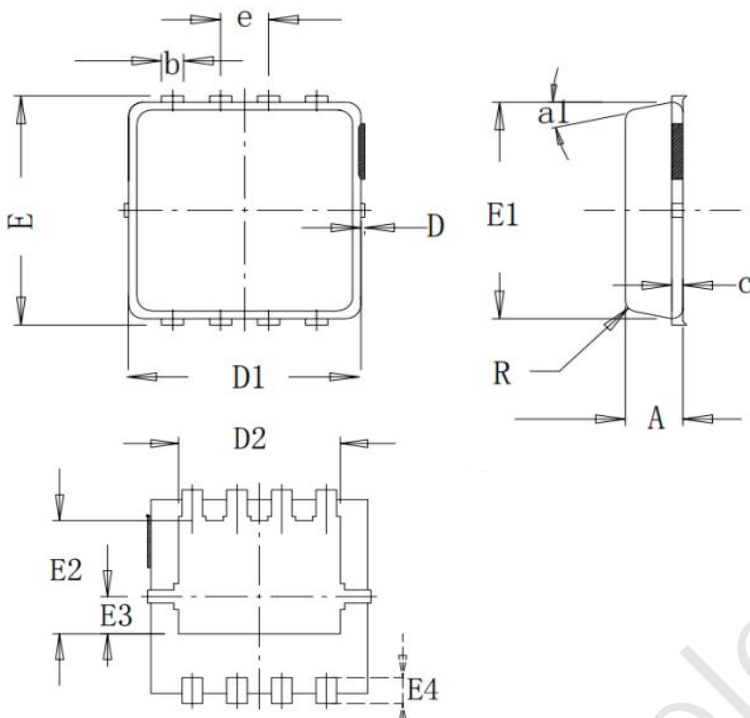


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

### Package Mechanical Data(PDFN3.3x3.3-8L)




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.75	0.78	0.81
* b	0.297	0.3	0.35
c	—	0.152	—
* D	0.00	0.05	0.1
D1	3.12	3.15	3.18
* D2	—	2.35	—
* E	3.2	3.3	3.4
E1	3.09	3.12	3.15
E2	—	1.75	—
E3	—	0.575	—
* E4	—	0.4	—
R	—	0.15	—
* e	0.65BSC		
a1°	—	12°	—

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For sales information, please send an email to: [sales@crm-semi.com](mailto:sales@crm-semi.com)